



DEFENSE LOGISTICS AGENCY  
LAND AND MARITIME  
POST OFFICE BOX 3990  
COLUMBUS, OH 43218-3990

March 5, 2020

Jerry Chang  
Silicon Turnkey Solutions  
General Manager  
1804 McCarthy Blvd  
Milpitas, CA 95035

Dear Mr. Chang:

Re: Laboratory Suitability for MIL-STD-883; FSC 5962; VQC-20-034741; Grammens  
CN: 071092

Silicon Turnkey Solutions (STS) has demonstrated to the DLA Land and Maritime compliance with MIL-STD-883, the test standard for integrated circuits. This letter supersedes the previous STS laboratory suitability, effective December 02, 2014 for the facilities, test methods and conditions shown on the enclosure. All testing must be performed in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

This letter is issued in conjunction with the QML certification letter DLA Land and Maritime- VQC-20-034740.

This Laboratory Suitability is subject to the policies, procedures, and conditions of the Defense Standardization Program, as published in the manual DoD 4120.24-M and SD-6.

This laboratory suitability is valid until terminated by written notice from DLA Land and Maritime. If warranted, it may be withdrawn by DLA Land and Maritime at any time. Each of these facilities is subject to an audit by DLA Land and Maritime with a minimum notice.

If you have any questions, please contact Mr. Grammens, (614) 692-0604.

Sincerely,

ROBERT M HEBER  
Chief  
Sourcing and Qualifications Division

Enclosure to DLA Land and Maritime-VQ (VQC-20-034741)

| Tests                           | Method/Condition   | Location     |
|---------------------------------|--|--------------|
| Temperature Cycling             | 1010/A-C   | STS          |
| Seal                            | 1014/A <sub>1</sub> , A <sub>2</sub> , C <sub>1</sub>            | STS          |
| Burn-in                         | 1015/A-F   | STS          |
| Constant Acceleration           | 2001/A-E   | STS          |
| External Visual                 | 2009   | STS          |
| Internal Visual                 | 2010 A,B   | STS          |
| Bond Strength                   | 2011/D, par 3.1.7 in accordance with JESD22-B116 Wire Bond Shear | STS          |
| NDBP                            | 2023   | STS          |
| Particle Impact Noise Detection | 2020/A, B  | STS          |
| Substrate Attach Strength       | 2027   | STS          |
| X-Ray                           | 2012   | Micross, NDT |
| Electrical Test                 | Per MIL-STD-883 Par 4.5 subgroups as specified in device spec    | STS          |

Micross

7725 N. Orange Blossom Trail  
Orlando, Florida

NDT

240 E. Caribbean Dr.  
Sunnyvale, California